

Appl. No.: 10/561,883
Amdt. Dated: December 2, 2009
Reply to Office Action of September 2, 2009

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AMENDMENTS

In the Specification:

Please add the following paragraphs at page 1, at the beginning of the Specification:

Cross-Reference to Related Applications

This application is derived from PCT patent application PCT/EP2004/007161 filed July 1st 2004 and claims priority from GB 0315623.9 filed July 3rd 2003.

Field of the Invention

This invention relates to die bonding.

Background of the Invention

Please insert the following heading on page 1, line 27 as follows:

Summary of the Invention

Please insert the following heading on page 4, line 21 as follows:

Brief Description of the Drawings

Please insert the following heading on page 5, line 4 as follows:

Detailed Description of Embodiments